Amendments to the Claims

Please amend the claims as follows:

1. (original)An apparatus including thermal stress protection, comprising:

a package;

a mass coupled to the package, the mass having a surface, the mass further including an active region; and

one or more substantially rigid members for attaching at least one point on the surface to the package to create a resilient coupling between the mass and the package, wherein at least a portion of the active region is spaced apart from the at least one point of attachment.

2. (original)The apparatus of claim 1, wherein the package comprises; a package including a cavity for receiving the mass.

3. (original)The apparatus of claim 1, wherein the package comprises:

a package including a recess for receiving the rigid member.

4. (original)The apparatus of claim 1, wherein the mass comprises one or more bond pads for coupling the mass to the package.

5. (original)The apparatus of claim 4, wherein the bond pads have a cross-sectional shape selected from the group consisting of approximately rectangular, approximately oval, approximately tri-oval, approximately oct-oval, approximately wavy sided rectangular, approximately oct-pie-wedge, approximately hollow oct-pie-wedge, approximately nine-circular, approximately starburst, or approximately sunburst.

6. (original)The apparatus of claim 4, wherein the mass comprises one or more passive regions; and

wherein the bond pads are approximately located in the passive regions.

Claim 7 is canceled.

8. (currently amended)The apparatus of claim 1 ~~7~~, wherein the ~~first~~ mass includes a passive region ~~is~~ located at one end of the mass.

9. (original)The apparatus of claim 4, wherein the mass further comprises a first passive region and a second passive region; and

wherein the bond pads are located in the first passive region and the second passive region.

10. (original)The apparatus of claim 9, wherein the first passive region is located at one end of the mass; and

wherein the second passive region is located at the opposite end of the mass.

11. (original)The apparatus of claim 4, wherein the mass further comprises a first passive region integral to the active region; and

wherein the bond pads are located in the first passive region.

12. (currently amended)The apparatus of claim 11, wherein the first passive region is located at one end of the mass; and

wherein the ~~first~~ active region is located at the opposite end of the mass.

13. (currently amended)The apparatus of claim 4, ~~wherein the mass further comprises an active region; and~~

~~———————~~wherein the bond pads are approximately located in the active region.

14. (original)The apparatus of claim 13, wherein the bond pads are located in the approximate center of the active region.

15. (original)The apparatus of claim 1, wherein the rigid members have a cross-sectional shape that is approximately rectangular or approximately circular.

16. (original)The apparatus of claim 1, wherein the rigid members are approximately located at one end of the package.

17. (original)The apparatus of claim 1, wherein the rigid members are approximately located at the approximate center of the package.

18. (original)The apparatus of claim 1, wherein there are one or more first rigid members and one or more second rigid members;

wherein the first rigid members are approximately located at one end of the package; and

wherein the second rigid members are approximately located at the opposite end of the package.

19. (original)The apparatus of claim 1, wherein the rigid members are a material selected from the group consisting of solder, conductive epoxy, non-conductive epoxy, and glass frit.

20. (original)The apparatus of claim 1, further comprising one or more sliding supports coupled to the package for slidingly supporting the mass.

21. (original)The apparatus of claim 20, wherein the sliding supports have a cross-sectional shape selected from the group consisting of approximate square, approximate circle, approximate triangle and approximate rectangle.

22. (original)The apparatus of claim 1, wherein the package comprises:

a package including a pedestal for supporting the rigid members.

23. (original) The apparatus of claim 1, wherein the mass is a micro-machined device, an integrated circuit chip, or an optical device.

24. (original)The apparatus of claim 1, wherein the rigid members further electrically couple the mass to the package.

25. (original)A method of coupling a mass having an active region to a package to reduce effects of thermal stress, comprising:

attaching at least one surface point on the mass to the package using one or more substantially rigid members to create a resilient coupling between the mass and the package, wherein at least a portion of the active region is spaced apart from the at least one point of attachment.

26. (original)The method of claim 25, wherein attaching the mass comprises attaching the mass at a plurality of locations.

27. (original)The method of claim 25, wherein the mass comprises a passive region, and wherein attaching the mass comprises attaching the passive region to the package.

28. (original)The method of claim 27, wherein the passive region is located at one end of the mass.

29. (original)The method of claim 25, wherein attaching the mass comprises attaching the active region to the package.

30. (original)The method of claim 29, wherein attaching the active region comprises attaching the approximate center of the active region to the package.

31. (original)The method of claim 25, wherein the mass comprises a first passive region and a second passive region; and

wherein attaching the mass comprises attaching the first passive region to the package and attaching the second passive region to the package.

32. (original)The method of claim 31, wherein the first passive region is located at one end of the mass; and

wherein the second passive region is located at an opposite end of the mass.

33. (original)The method of claim 25, wherein the mass further comprises a passive region integral to the active region; and

wherein attaching the mass comprises attaching the passive region to the package.

34. (original)The method of claim 33, wherein the passive region is at one end of the mass; and

wherein the active region is at the opposite end of the mass.

35. (original)The method of claim 25, wherein attaching the mass comprises permitting the mass to expand and contract without inducing stresses in the mass.

36. (original)The method of claim 25, wherein attaching the mass comprises providing for expansion and contraction of the package without inducing stresses in the mass.

37. (original)The method of claim 25, further comprising slidingly supporting the mass at one or more different locations.

38. (original)The method of claim 37, wherein slidingly supporting the mass comprises slidingly supporting the mass at a plurality of locations.

39. (original)The method of claim 37, wherein slidingly supporting the mass comprises providing for expansion and contraction without inducing stresses in the package.

40. (original)The method of claim 25, wherein attaching the mass comprises providing for expansion and contraction without inducing stresses in the package.

41. (original)The method of claim 25, further comprising electrically coupling the mass to the package at one or more different locations.

42. (new)An apparatus including thermal stress protection, comprising:

a package;

a mass coupled to the package, the mass having a surface, the mass further including an active region and a passive region; and

one or more substantially rigid members for attaching at least one point on the surface to the package to create a resilient coupling between the mass and the package, wherein the at least one point of attachment is in the passive region and at least a portion of the active region is spaced apart from the at least one point of attachment.

43. (new)A method of coupling a mass having an active region and a passive region to a package to reduce effects of thermal stress, comprising:

attaching at least one surface point on the mass to the package using one or more substantially rigid members to create a resilient coupling between the mass and the package, wherein the at least one point of attachment is in the passive region and at least a portion of the active region is spaced apart from the at least one point of attachment.